ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES®	PC. Bannockł	burn, Illinois, A	ll rights reserved nations.	under both	This docume level parts, t	ent is a declaration er	on of the su	bstances v all lower	vithin the manufactu level materials for w	rer listed it which the m	em. Note: anufacture	if the item is an as r has engineering	sembly with low responsibility.
	P1.1IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175xForm T Distribution				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information													
Company name* Compan			mpany unique ID			Unique ID Authority				Response Date*			
semi										2025-06-06			
Contact Name	t Name Title - Contact]	Phone - Contact*				Email - Contact*			
roduct-Env-Stewards Product Enviro Co			o Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			sentative	ntative		Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product En			act Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	n Number	Mfr Item Name			Effective Date	Version Manufacturing Site		7	Weight*	UOM	Unit Type	
	NZ8P24	NZ8P24VMX2WT5G Zener Protection		Diode		2025-06-06		CI	CN1).879	mg	Each
Ianufacturing Proccess Informat	tion		·				·						
Terminal Plating / Grid Array Ma	terial 7	al Terminal Base Alloy		J-STD-020 MS	STD-020 MSL Rating		Peak Process Body Temperature		e Max Time at Peak Tempera		ure Num	ber of Reflow Cyc	eles
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	secon	ds 3			
omments													
vel 1 - maximum time at peak temperatu	re during so	ldering is 10-3	0 seconds										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	toHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.015	mg	Supplier	Silicon (Si)	7440-21-3		0.015	mg
Die Attach	0.008	mg		Epoxy resin	proprietary data		0.0012	mg
			Supplier	Silver (Ag)	7440-22-4		0.0064	mg
			Supplier	Bismaleimide	13676-54-5		0.0004	mg
Lead Frame	0.458	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0008	mg
			Supplier	Silicon (Si)	7440-21-3		0.0034	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0005	mg
			В	Nickel (Ni)	7440-02-0		0.0149	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.4384	mg
Mold Compound-Black	0.34	mg	Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0255	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0017	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.2703	mg
			Supplier	EpoxyNovolaCresins (Cresolic)	64425-89-4		0.017	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0255	mg
Plating	0.053	mg	Supplier	Tin (Sn)	7440-31-5		0.053	mg
Wire Bond - Cu	0.005	mg	Supplier	Copper (Cu)	7440-50-8		0.005	mg